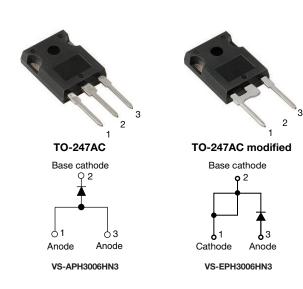


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Hyperfast Rectifier, 30 A FRED Pt®



PRODUCT SUMMARY						
Dankaga	TO-247AC,					
Package	TO-247AC modified (2 pins)					
I _{F(AV)}	30 A					
V_{R}	600 V					
V _F at I _F	2.65 V					
t _{rr} typ.	27 ns					
T _J max.	175 °C					
Diode variation	Single die					

FEATURES

- · Low forward voltage drop
- Hyperfast soft recovery time
- 175 °C operating junction temperature
- AEC-Q101 qualified, meets JESD 201 class 1 whisker test
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

DESCRIPTION/APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 112 °C	30	۸			
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	220	Α			
Operating junction and storage temperatures	T _J , T _{Stg}		- 65 to 175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-			
Forward voltage	V _F	I _F = 30 A - 2.0		2.0	2.65	V		
	VF	I _F = 30 A, T _J = 150 °C	-	1.4	1.8			
	-	$V_R = V_R$ rated	-	-	30			
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	300	300 µA		
Junction capacitance	C _T	V _R = 600 V	-	20	=	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ		



VS-APH3006HN3, VS-EPH3006HN3

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1 \text{ A}, dI_F/dt = 50$	0 A/μs, V _R = 30 V	-	26	35			
Reverse recovery time	t _{rr}	T _J = 25 °C		-	26	-	ns		
		T _J = 125 °C		-	70	-			
Dools woods on a commont		T _J = 25 °C	I _F = 30 A	-	3.5	-	^		
Peak recovery current	I _{RRM}	T _J = 125 °C	dI _F /dt = 200 A/µs V _R = 200 V	-	7.6	-	Α		
B		T _J = 25 °C		-	50	-	nC		
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	280	-	nc nc		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		- 65	-	175	°C		
Thermal resistance, junction to case	R _{thJC}		-	0.7	1.1	°C/W		
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-			
Woight			-	5.5	-	g		
Weight			-	0.2	-	OZ.		
Mounting torque			1.2 (10)	-	2.4 (20)	kgf · cm (lbf · in)		
Marking daying		Case style TO-247AC	APH3006H					
Marking device		Case style TO-247AC modified		EPH	3006H			

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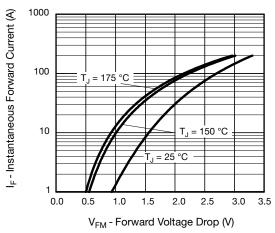


Fig. 1 - Typical Forward Voltage Drop Characteristics

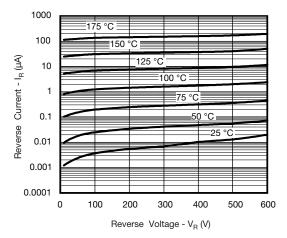


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

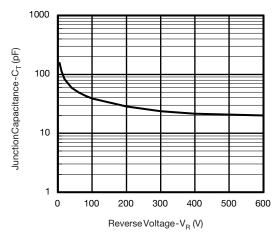


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

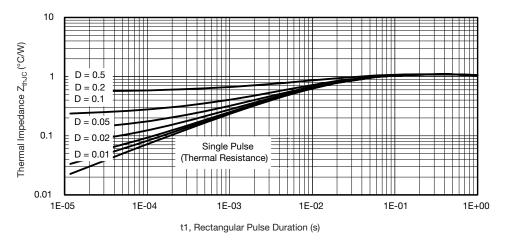


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

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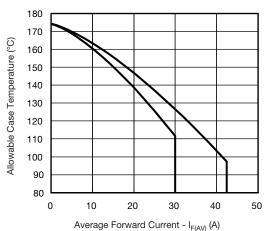


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

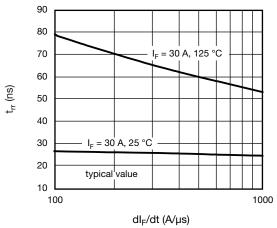


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

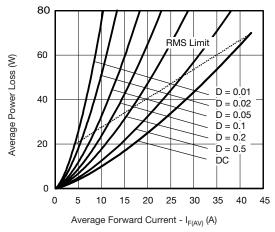


Fig. 6 - Forward Power Loss Characteristics

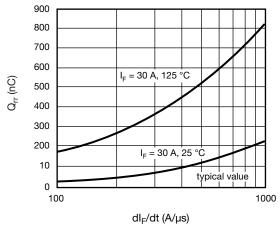
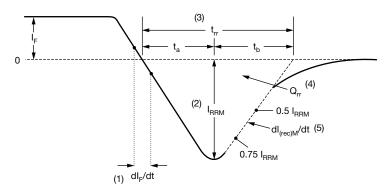


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $t_{\rm rr}$ reverse recovery time measured from zero crossing point of negative going $I_{\rm F}$ to point where a line passing through 0.75 $I_{\rm RRM}$ and 0.50 $I_{\rm RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RBM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

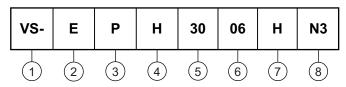
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-APH3006HN3, VS-EPH3006HN3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

• A = Single diode

• E = Single diode (modified)

3 - P = TO-247AC

4 - H = Hyperfast recovery time

5 - Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

7 - H = AEC-Q101 qualified

8 - Environmental digit:

N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N QUANTITY PER TUBE MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION						
VS-APH3006HN3	25	500	Antistatic plastic tube			
VS-EPH3006HN3	25	500	Antistatic plastic tube			

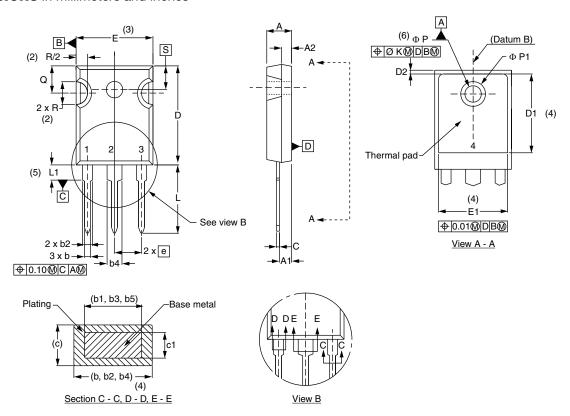
LINKS TO RELATED DOCUMENTS				
Dimensions	TO-247AC	www.vishay.com/doc?95542		
Dimensions	TO-247AC modified	www.vishay.com/doc?95541		
Part marking information	TO-247AC	www.vishay.com/doc?95007		
Part marking information	TO-247AC modified	www.vishay.com/doc?95442		



Vishay Semiconductors

TO-247AC

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOIES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.530	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	0.254)10	
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51	BSC	0.217 BSC		

Notes

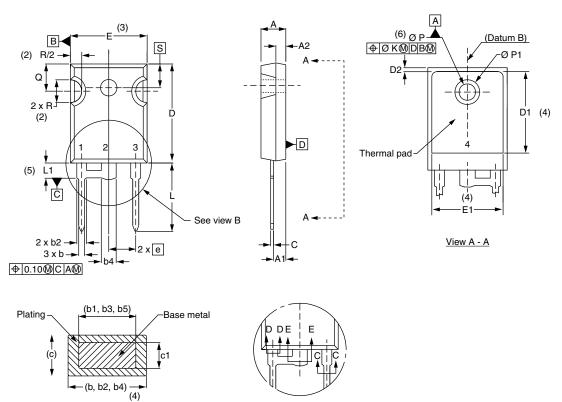
- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- $^{(7)}$ Outline conforms to JEDEC® outline TO-247 with exception of dimension c



Vishay Semiconductors

TO-247AC modified

DIMENSIONS in millimeters and inches



View B

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

Section C - C, D - D, E - E

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.530	-	
е	5.46 BSC		0.215	BSC	
ØK	0.254		0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	ı	6.98	-	0.275	
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Notes

- (1) Dimensioning and tolerance per ASME Y14.5M-1994
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